

**Glued SAM data sheet SAM- $\lambda$ -A- $\tau$ -4.0-25.4g-c or SAM- $\lambda$ -A- $\tau$ -4.0-25.4g-e**

SAM chip area	standard:	4.0 mm x 4.0 mm
	optional:	other dimensions on request

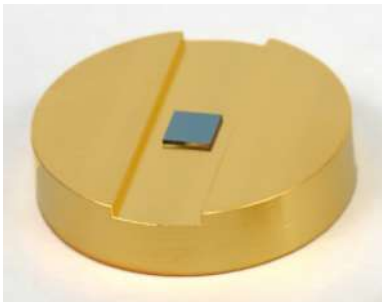
Chip thickness standard: 450  $\mu\text{m}$

Front side protection The SAM is protected with a dielectric front layer.

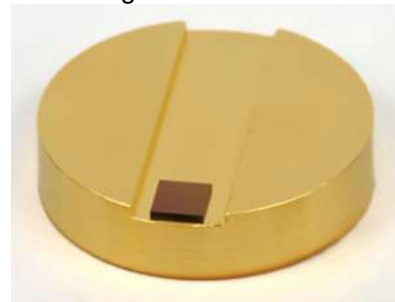
The SAM chip is glued on a gold plated Cu-cylinder with  $\varnothing$  25.4 mm using a thermal conducting adhesive. The adhesive provides a low thermal resistance between the SAM and the mount.

- The **standard** position of the SAM is in the center of the mount  $\rightarrow$  x = 4.0-25.4g-c.
- **Optional** the SAM can be soldered at the edge of the mount without extra charges  $\rightarrow$  x = 4.0-25.4g-e.

Center mounted SAM



Edge mounted SAM



Dimensions:

